



BYC60W-600P

Hyperfast power diode

Rev.01 - 4 March 2019

Product data sheet

1. General description

Hyperfast power diode in a SOD142 (2-lead TO247) plastic package.

2. Features and benefits

- Fast switching and soft reverse recovery characteristics
- Low forward voltage drop
- Low leakage current
- Low reverse recovery current
- Reduces switching losses in associated MOSFET or IGBT
- High operating temperature capability ($T_{j(max)} = 175^{\circ}\text{C}$)

3. Applications

- UPS
- EV Charger
- Welding Machine
- Air Conditioner

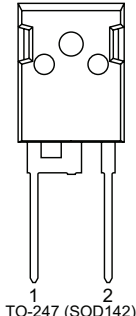
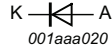
4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Values			Unit
Absolute maximum rating						
V_{RRM}	repetitive peak reverse voltage		600			V
$I_{F(AV)}$	average forward current	$\delta = 0.5$; square-wave pulse; $T_{mb} \leq 116^{\circ}\text{C}$; Fig. 1 ; Fig. 2 ; Fig. 3	60			A
I_{FRM}	repetitive peak forward current	$\delta = 0.5$; $t_p = 25 \mu\text{s}$; $T_{mb} \leq 116^{\circ}\text{C}$; square-wave pulse	120			A
I_{FSM}	non-repetitive peak forward current	$t_p = 10 \text{ ms}$; $T_{j(\text{init})} = 25^{\circ}\text{C}$; sine-wave pulse; Fig. 4	600			A
		$t_p = 8.3 \text{ ms}$; $T_{j(\text{init})} = 25^{\circ}\text{C}$; sine-wave pulse;	660			A
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
V_F	forward voltage	$I_F = 60 \text{ A}$; $T_j = 25^{\circ}\text{C}$; Fig. 6	-	2	2.4	V
		$I_F = 60 \text{ A}$; $T_j = 150^{\circ}\text{C}$; Fig. 6	-	1.55	2	V
Dynamic characteristics						
t_{rr}	reverse recovery time	$I_F = 1 \text{ A}$; $V_R = 30 \text{ V}$; $di_F/dt = 50 \text{ A}/\mu\text{s}$; $T_j = 25^{\circ}\text{C}$; Fig. 7	-	-	50	ns

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode	 <p>TO-247 (SOD142)</p>	 001aaa020
2	A	anode		
mb	mb	mounting base; connected to cathode		

6. Ordering information

Table 3. Ordering information

Type number	Package name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
BYC60W-600P	TO247	BYC60W-600PQ	Tube	30	SOD142	27-Nov-2012

7. Marking

Table 4. Marking codes

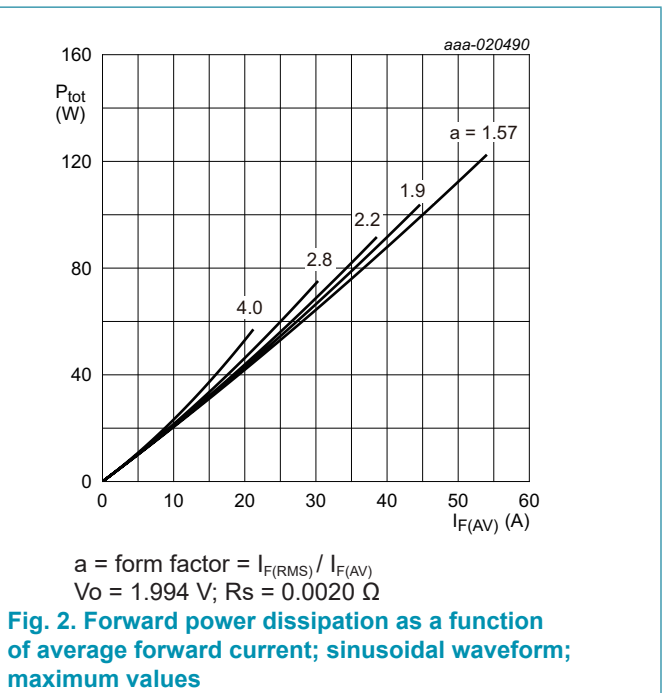
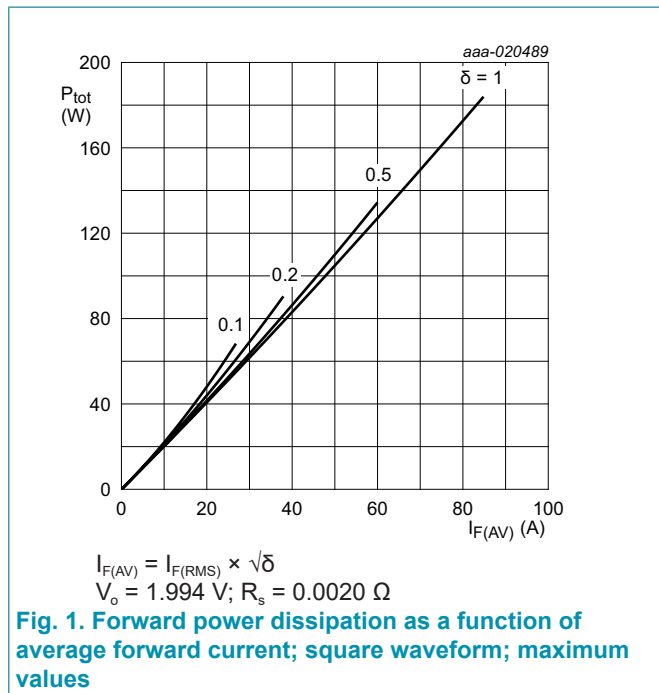
Type number	Marking codes
BYC60W-600P	BYC60W-600P

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Values	Unit
V_{RRM}	repetitive peak reverse voltage		600	V
V_{RWM}	crest working reverse voltage		600	V
V_R	reverse voltage	DC	600	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$; square-wave pulse; $T_{mb} \leq 116\text{ }^\circ\text{C}$; Fig. 1 ; Fig. 2 ; Fig. 3	60	A
I_{FRM}	repetitive peak forward current	$\delta = 0.5$; $t_p = 25\text{ }\mu\text{s}$; $T_{mb} \leq 116\text{ }^\circ\text{C}$; square-wave pulse	120	A
I_{FSM}	non-repetitive peak forward current	$t_p = 10\text{ ms}$; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$; sine-wave pulse; Fig. 4	600	A
		$t_p = 8.3\text{ ms}$; $T_{j(\text{init})} = 25\text{ }^\circ\text{C}$; sine-wave pulse;	660	A
I^2t	limiting Joule-integral	SIN; $t_p = 10\text{ ms}$	1800	A^2s
T_{stg}	storage temperature		-55 to 175	$^\circ\text{C}$
T_j	junction temperature		175	$^\circ\text{C}$



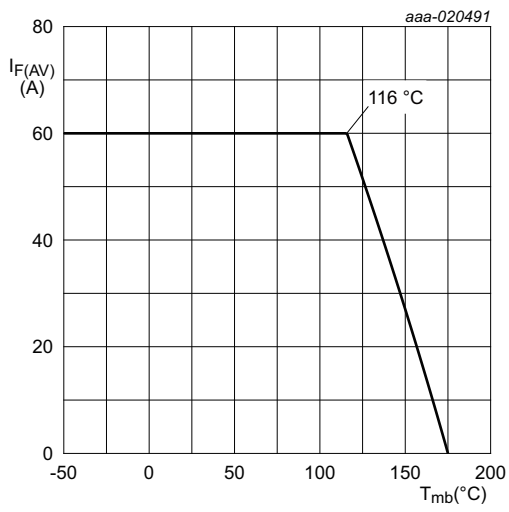


Fig. 3. Forward current as a function of mounting base temperature; maximum values

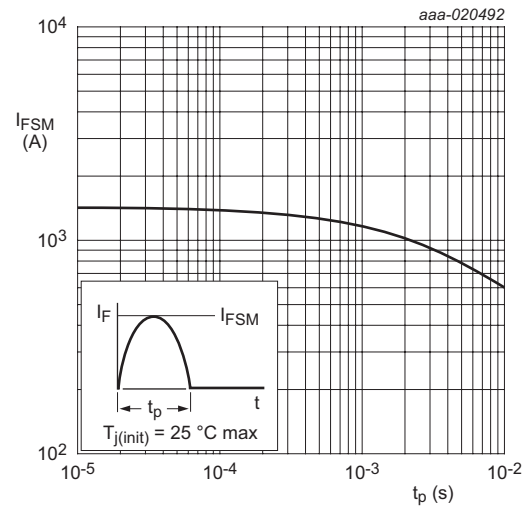
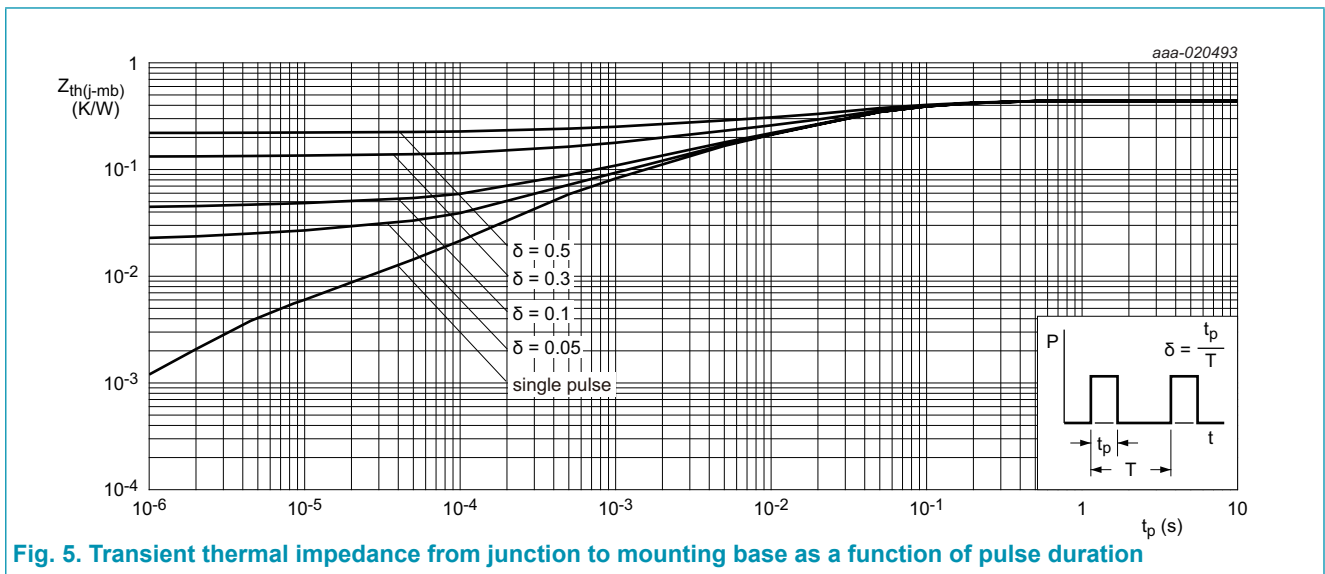


Fig. 4. Non-repetitive peak forward current as a function of pulse width; sinusoidal waveform; maximum values

9. Thermal characteristics

Table 6. Thermal characteristics

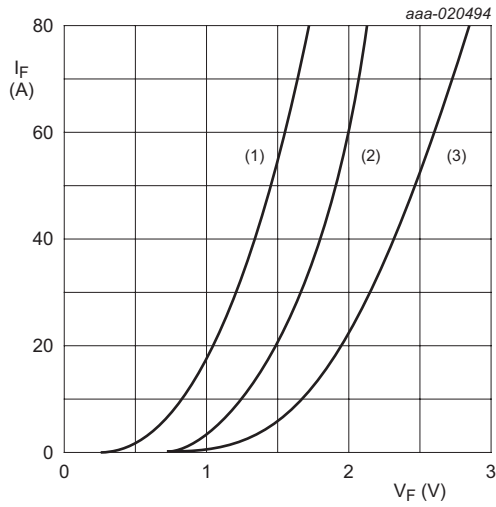
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	Fig. 5	-	-	0.44	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air	-	45	-	K/W



10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
V_F	forward current	$I_F = 60 \text{ A}; T_j = 25 \text{ }^\circ\text{C}; \text{Fig. 6}$	-	2	2.4	V
		$I_F = 60 \text{ A}; T_j = 150 \text{ }^\circ\text{C}; \text{Fig. 6}$	-	1.55	2	V
I_R	reverse current	$V_R = 600 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$	-	2	10	μA
		$V_R = 600 \text{ V}; T_j = 150 \text{ }^\circ\text{C}$	-	-	500	μA
Dynamic characteristics						
Q_r	reverse charge	$I_F = 60 \text{ A}; V_R = 400 \text{ V}; di_F/dt = 200 \text{ A}/\mu\text{s}; T_j = 25 \text{ }^\circ\text{C}; \text{Fig. 7}$	-	74	-	nC
		$I_F = 60 \text{ A}; V_R = 400 \text{ V}; di_F/dt = 200 \text{ A}/\mu\text{s}; T_j = 125 \text{ }^\circ\text{C}; \text{Fig. 7}$	-	559	-	nC
t_{rr}	reverse recovery time	$I_F = 1 \text{ A}; V_R = 30 \text{ V}; di_F/dt = 50 \text{ A}/\mu\text{s}; T_j = 25 \text{ }^\circ\text{C}; \text{Fig. 7}$	-	-	50	ns
		$I_F = 60 \text{ A}; V_R = 400 \text{ V}; di_F/dt = 200 \text{ A}/\mu\text{s}; T_j = 25 \text{ }^\circ\text{C}; \text{Fig. 7}$	-	40	-	ns
		$I_F = 60 \text{ A}; V_R = 400 \text{ V}; di_F/dt = 200 \text{ A}/\mu\text{s}; T_j = 125 \text{ }^\circ\text{C}; \text{Fig. 7}$	-	101	-	ns
I_{RM}	peak reverse recovery current	$I_F = 60 \text{ A}; V_R = 400 \text{ V}; di_F/dt = 200 \text{ A}/\mu\text{s}; T_j = 25 \text{ }^\circ\text{C}; \text{Fig. 7}$	-	3.7	-	A
		$I_F = 60 \text{ A}; V_R = 400 \text{ V}; di_F/dt = 200 \text{ A}/\mu\text{s}; T_j = 125 \text{ }^\circ\text{C}; \text{Fig. 7}$	-	11	-	A



$V_o = 1.994 \text{ V}; R_s = 0.0020 \text{ } \Omega$
 (1) $T_j = 150 \text{ } ^\circ\text{C}$; typical values
 (2) $T_j = 150 \text{ } ^\circ\text{C}$; maximum values
 (3) $T_j = 25 \text{ } ^\circ\text{C}$; maximum values

Fig. 6. Forward current as a function of forward voltage

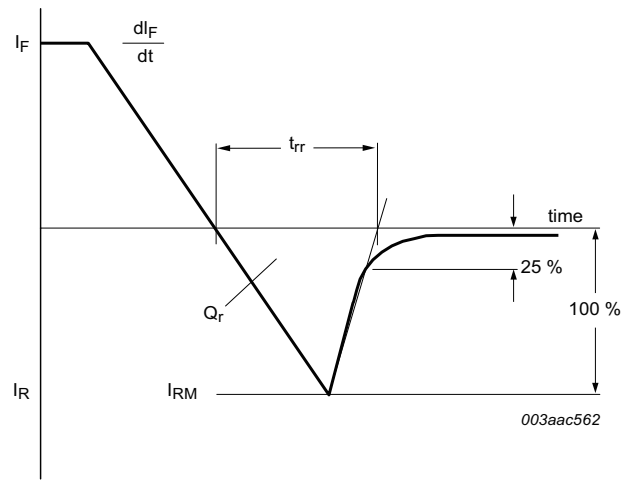
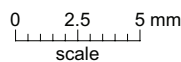
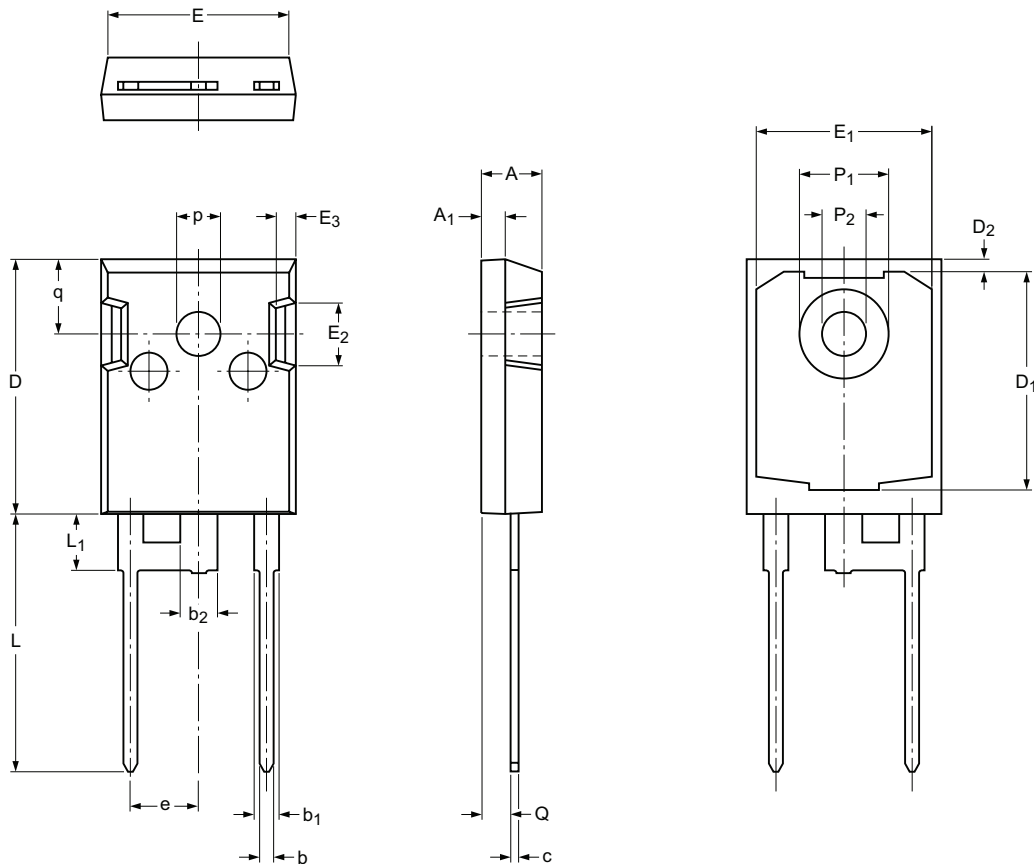


Fig. 7. Reverse recovery definitions; ramp recovery

11. Package outline

Plastic Single-ended through-hole package; Heatsink mounted; 1 mounting hole; 2-lead TO-247

SOD142



Dimensions (mm are the original dimensions)

Unit	A	A ₁	b	b ₁	b ₂	c	D	D ₁	D ₂	e	E	E ₁	E ₂	E ₃	L	L ₁	p	p ₁	p ₂	q	Q	
mm	max	5.2	2.1	1.4	2.2	3.2	0.7	20.6	17.68	1.2	15.75	14.22	5.2	1.8	20.9	4.75	3.7	7.3	3.6	6.18	2.6	
	nom									5.45												
	min	4.7	1.9	1.0	1.8	2.8	0.5	20.3	17.28	0.8	15.45	13.82	4.8	1.4	20.4	4.25	3.5	7.1	3.4	5.78	2.2	

sod142_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOD142		TO247			12-11-13 12-11-27

12. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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